

**AMENDMENT TO THE TITLE OF THE INVENTION**

Please replace the title of the invention with the following amended title:

**PRINTED CIRCUIT BOARD**

**AMENDMENT TO THE SPECIFICATION**

Please replace the paragraph beginning at page 3, line 36, with the following amended paragraph:

Figure 1 shows a cross-sectional view of section at right angles through a printed circuit for a first embodiment of a printed circuit 1 according to the invention with surface mounted devices 2 which are fitted to the inner face 3a of a film 3x, 3y. The surface mounted devices 2 are arranged between two films 3x, 3y and are embedded in a dielectric 4. The connection between the surface mounted device 2 and the film 3x, 3y is a soldered joint 5. Figure 2 shows a cross-sectional view of section at right angles through a second embodiment of a printed circuit according to the invention with surface mounted devices 2 which are fitted to the inner faces 3a, 3b of both films. As shown in Figure 2, the devices 2, or electrical components, are mutually opposite.

Please replace the paragraph beginning at page 4, line 11, with the following amended paragraph:

Figure 3 shows a cross-sectional view of section at right angles through a printed circuit 1 according to the invention with contacts 6a, 6b. In this case, first contacts 6a are provided on the outer faces 3c, 3d of the films 3x, 3y. Further microchips 7 or further soldered joints 8, for example, may be fitted to these contacts 6a. Via holes 6b form a direct connection between the two films 3x, 3y. On its path from one film 3x to the opposite film 3y a signal thus passes over the shortest possible distance. In this case, the signal passes through a single via hole 6b between the two films 3x, 3y.

Please replace the paragraph beginning at page 4, line 23, with the following amended paragraph:

Figure 4 shows a cross-sectional view of section at right angles through a further exemplary embodiment of a printed circuit 1 according to the invention. Further layers composed of dielectric 4 and film 3z are applied to the outer faces 3c, 3d of the pressed films 3x, 3y. Contacts 6c, for example via holes, can expediently be formed between the films 3z and the pressed films 3x, 3y.